

In the Claims:

Please cancel claims 1-61 and 88-123, and please amend claims 62, 64, 67, 68, 71 and 72 as follows:

1-61. (Canceled)

62. (Currently amended) An electronic device, comprising:

a housing;

a microelectronic substrate positioned within the housing;

a support ~~members~~substrate carrying the microelectronic substrate in the housing; and

a connection structure carried by the support ~~members~~substrate, the connection structure having a bond site configured to receive a flowable conductive material, the connection structure further having at least two elongated members, each of which is connected to and extends outwardly from the bond site, each elongated member being configured to receive at least a portion of the flowable conductive material from the bond site, and neither of which is electrically connected to the microelectronic substrate.

63. (Original) The device of claim 62 wherein each elongated member is configured to receive at least a portion of the flowable conductive material from the bond site.

64. (Currently amended) The device of claim 62 wherein the connection structure is a first connection structure and the elongated members are first elongated members configured to receive at least a portion of the flowable conductive material from the first bond site, and wherein the apparatus further comprises a second connection structure carried by the support ~~members~~substrate, the second connection structure having a second bond site configured to receive a flowable conductive material, the second connection structure having a third bond site electrically coupled

to the microelectronic substrate, the second connection structure further having second elongated members extending outwardly from the second bond site, wherein each of the second elongated members is configured to receive at least a portion of the flowable conductive material, and wherein and at least one of the second elongated members extends between the second and third bond sites.

65. (Original) The device of claim 62 wherein the elongated members are configured to be wetted by the flowable conductive material when the flowable conductive material is in a flowable state.

66. (Original) The device of claim 62 wherein the conductive structure includes two elongated members extending away from opposite sides of the bond site.

67. (Currently amended) The device of claim 62, further comprising a layer disposed on the elongated members and attached to the support ~~members~~substrate, the layer having an aperture aligned with the bond site.

68. (Currently amended) The device of claim 62, further comprising a layer disposed on the elongated members and attached to the support ~~members~~substrate, the layer having an aperture aligned with the bond site, and wherein a covered portion of each elongated member extends between the layer and the support ~~members~~substrate, and an exposed portion of each elongated member is exposed through the aperture, further wherein each exposed portion has approximately the same length.

69. (Original) The device of claim 62 wherein the connection structure includes at least one electrically conductive metallic material.

70. (Original) The device of claim 62 wherein the bond site includes a solder ball pad, and wherein the apparatus further comprises a solder ball disposed on the solder ball pad.

71. (Currently amended) The device of claim 62 wherein at least one of the elongated members has a first end connected to the bond site and a second end spaced apart from the bond site, and wherein the elongated member includes an anchor toward the second end to secure the elongated member to the support membersubstrate.

72. (Currently amended) The device of claim 62 wherein the support membersubstrate has a first surface ~~that includes the support surface, the support member further having~~coupled to the microelectronic substrate and a second surface facing opposite from the first surface, the connection structure being disposed on the second surface, and wherein the support membersubstrate includes a slot extending between the first and second surfaces, and wherein the deviceapparatus further comprises wires extending through the slot between the second connection structure and the microelectronic substrate.

73. (Original) A microelectronic assembly, comprising:

- a microelectronic substrate having a first surface, a second surface facing opposite from the first surface, and a first bond site positioned at least proximate to the second surface; and
- a connection structure disposed on the second surface of the microelectronic substrate, the connection structure having a second bond site configured to receive a flowable conductive material, the connection structure further having at least two elongated members connected to and extending outwardly from the second bond site.

74. (Original) The assembly of claim 73 wherein each elongated member is configured to receive at least a portion of the flowable conductive material from the second bond site.

75. (Original) The assembly of claim 73 wherein at least one of the elongated members is electrically coupled to the first bond site of the microelectronic substrate.

76. (Original) The assembly of claim 73 wherein none of the elongated members of the connection structure are connected to any bond sites of the microelectronic substrate.

77. (Original) The assembly of claim 73, further comprising a volume of flowable conductive material disposed on the second bond site.

78. (Original) The assembly of claim 73 wherein the connection structure includes a metal redistribution layer deposited on the microelectronic substrate.

79. (Original) The assembly of claim 73 wherein the microelectronic substrate has a first surface and a second surface facing opposite from the first surface, and wherein the first bond site is positioned at least proximate to the second surface, further wherein the elongated members are spaced apart from the second surface in a plane generally parallel to the second surface.

80. (Original) The assembly of claim 73 wherein the microelectronic substrate has a first surface and a second surface facing opposite from the first surface, and wherein the first bond site is positioned at least proximate to the second surface, and wherein the elongated members each have a first surface and a second surface facing opposite from the first surface, and wherein the assembly further comprises:

a first passivation layer between the second surface of the microelectronic substrate and the first surfaces of the elongated members;

a second passivation layer adjacent to the second surfaces of the elongated members; and

a conductive coupler disposed on the second bond site, the conductive coupler including a flowable conductive material.

81. (Original) The assembly of claim 73 wherein the microelectronic substrate has a first surface and a second surface facing opposite from the first surface, and wherein the first bond site is positioned at least proximate to the second surface in a first plane generally parallel to the second surface, further wherein the second bond site is positioned in a second plane generally parallel to and spaced apart from the first plane.

82. (Original) An apparatus for supporting a microelectronic substrate, comprising:

a support member having a first surface and a second surface facing opposite from the first surface, the second surface being configured to carry a microelectronic substrate; and

a connection structure carried by the support member, the connection structure including:

first and second bond sites, the first bond site being positioned at least proximate to the first surface of the support member, the second bond site being positioned at least proximate to the second surface of the support member, the second bond site being configured to be electrically coupled to the microelectronic substrate when the support member carries the microelectronic substrate, the first bond site being configured to receive a flowable conductive material; and

at least two elongated members connected to and extending outwardly from the first bond site, at least one of the elongated members being coupled between the first and second bond sites.

83. (Original) The apparatus of claim 82 wherein the at least one elongated member includes a first portion in a first plane generally parallel to the first surface, a

second portion in a second plane generally parallel to the second surface and spaced apart from the first plane, and a third portion connected between the first and second portions.

84. (Original) The apparatus of claim 82, further comprising a solder ball disposed on the first bond site.

85. (Original) The apparatus of claim 82, further comprising:
a microelectronic substrate carried by the support member; and
a conductive link electrically coupled between the microelectronic substrate and
the second bond site.

86. (Original) The apparatus of claim 82, further comprising:
a microelectronic substrate carried by the support member; and
a wire bond electrically coupled between the microelectronic substrate and the
second bond site.

87. (Original) The apparatus of claim 82 wherein each elongated member is configured to receive at least a portion of a flowable material from the first bond site.

88-123. (Canceled)